/ Descriptions

SOT-23 P

P- CHANNEL MOSFET in a SOT-23 Plastic Package.

/ Features

V_{DS}=-30V I_D=-3.2A

$R_{DS(ON)}$@-10V≤90mΩ(Typ.54mΩ)

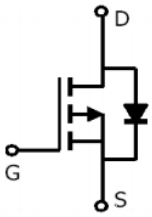
$R_{DS(ON)}$@-4.5V≤110mΩ(Typ.63mΩ)

HF Product.

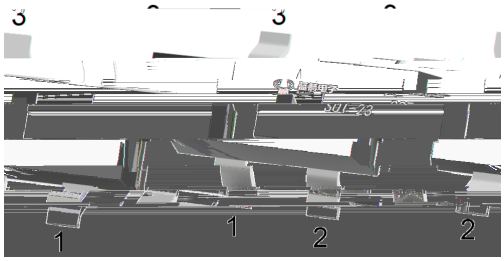
/ Applications

Notebook,Load Switch,Battery Protection,Hand-held Instruments.

/ Equivalent Circuit



/ Pinning



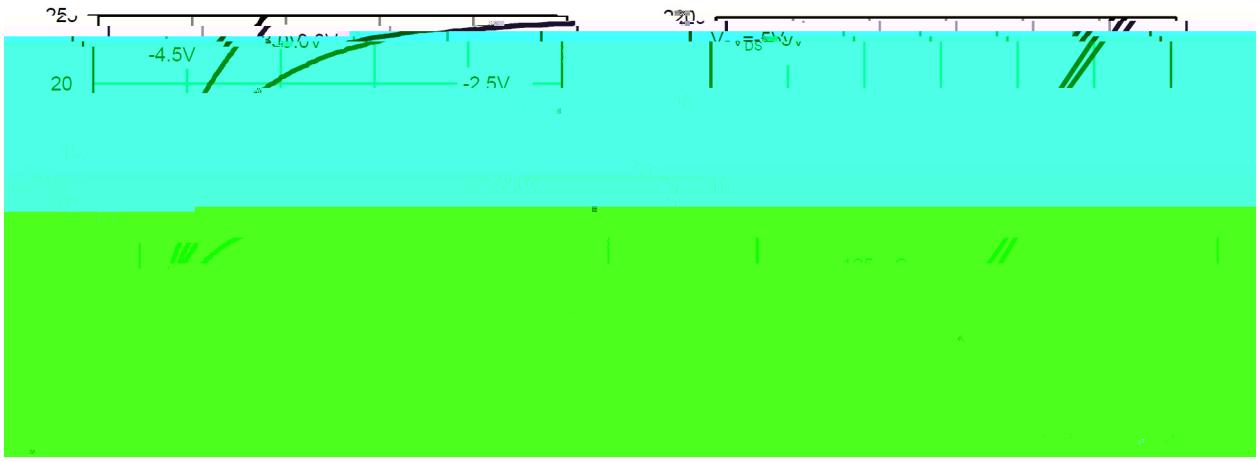
PIN1 G PIN 2 S PIN 3 D

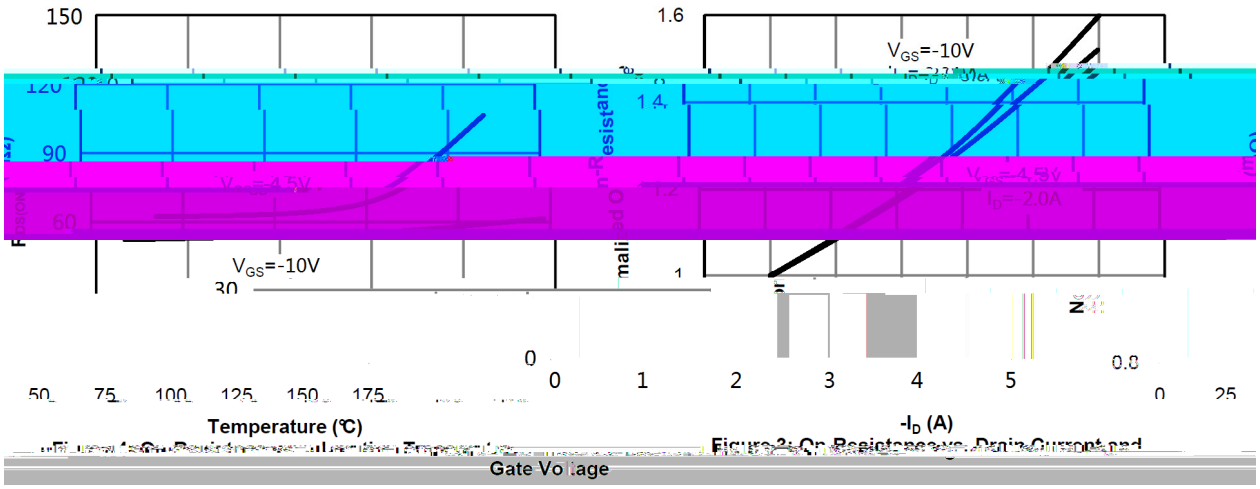
/ Marking

See Marking Instructions.

Parameter	Symbol	Rating	Unit
Drain–Source Voltage	V_{DSS}	-30	V
Gate–Body Leakage Voltage	V_{GSS}	±12	V
Drain Current – Continuous	I_D	-3.2	A
Pulsed Drain Current	I_{DM}	-13.2	A
Power Dissipation	P_D	1.5	W
Operating and Storage Temperature Range	T_J,T_{STG}	-55 150	
Maximum Junction-to-Ambient t ≤ 10s	R		

/ Electrical Characteristic Curve





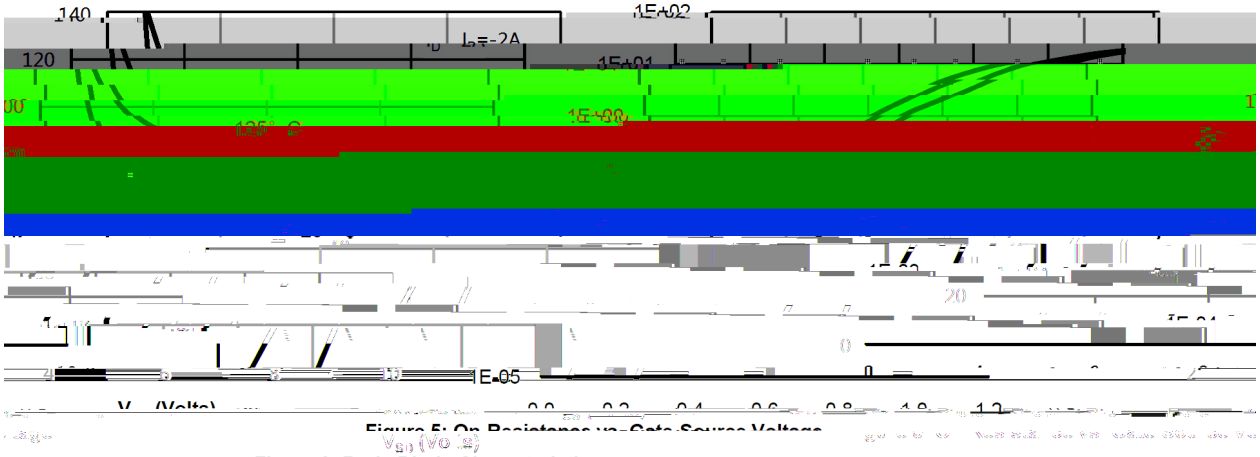
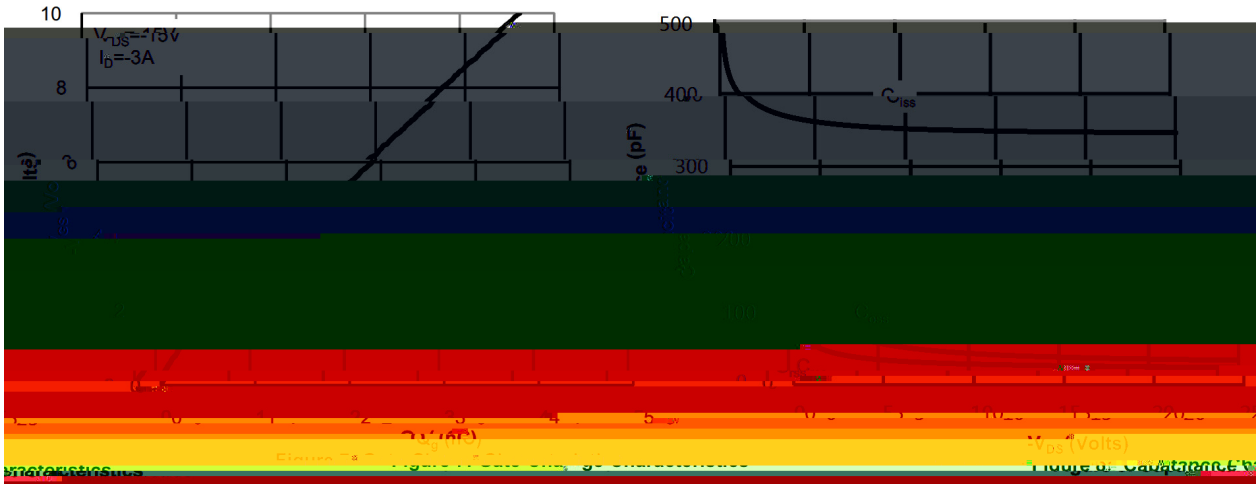
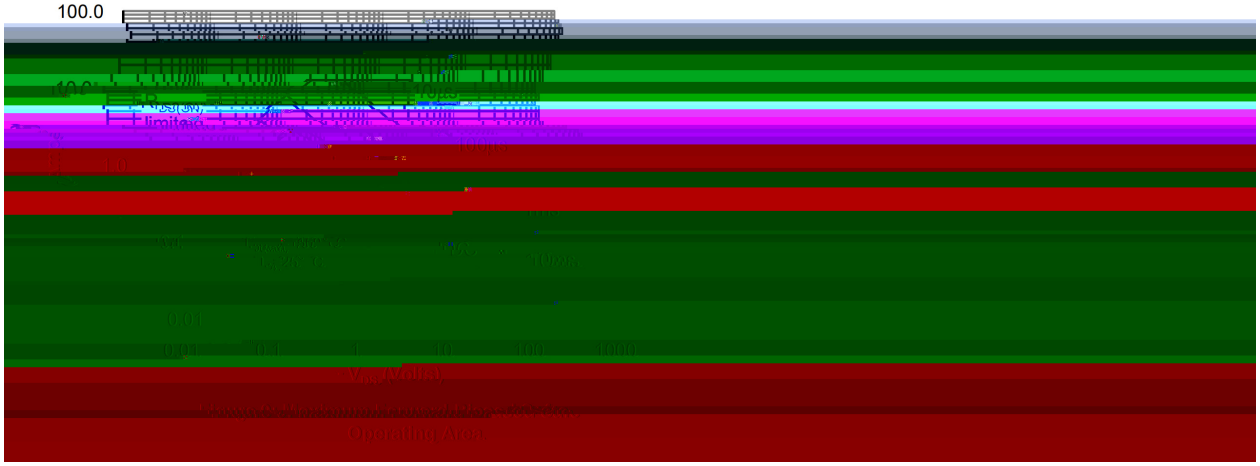
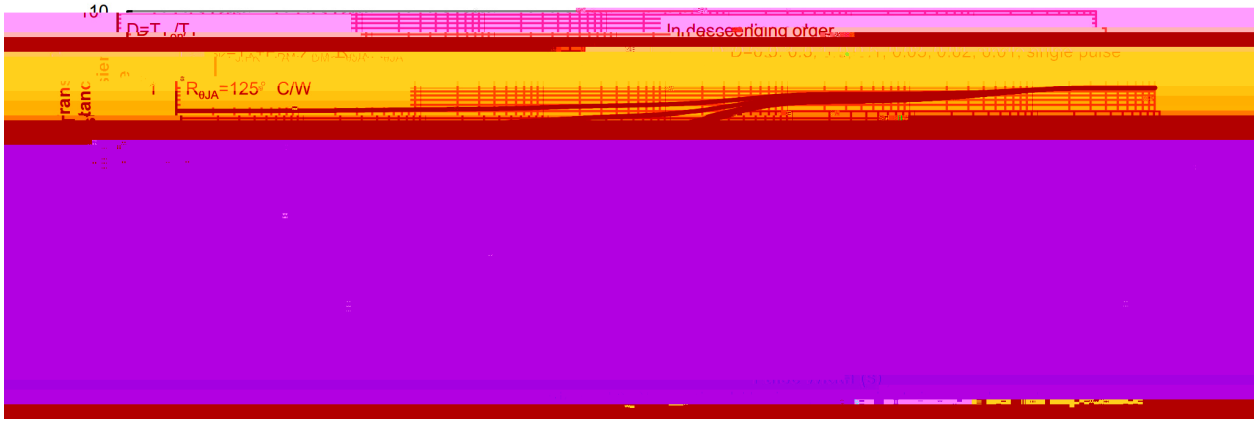


Figure 6: Body-Diode Characteristics

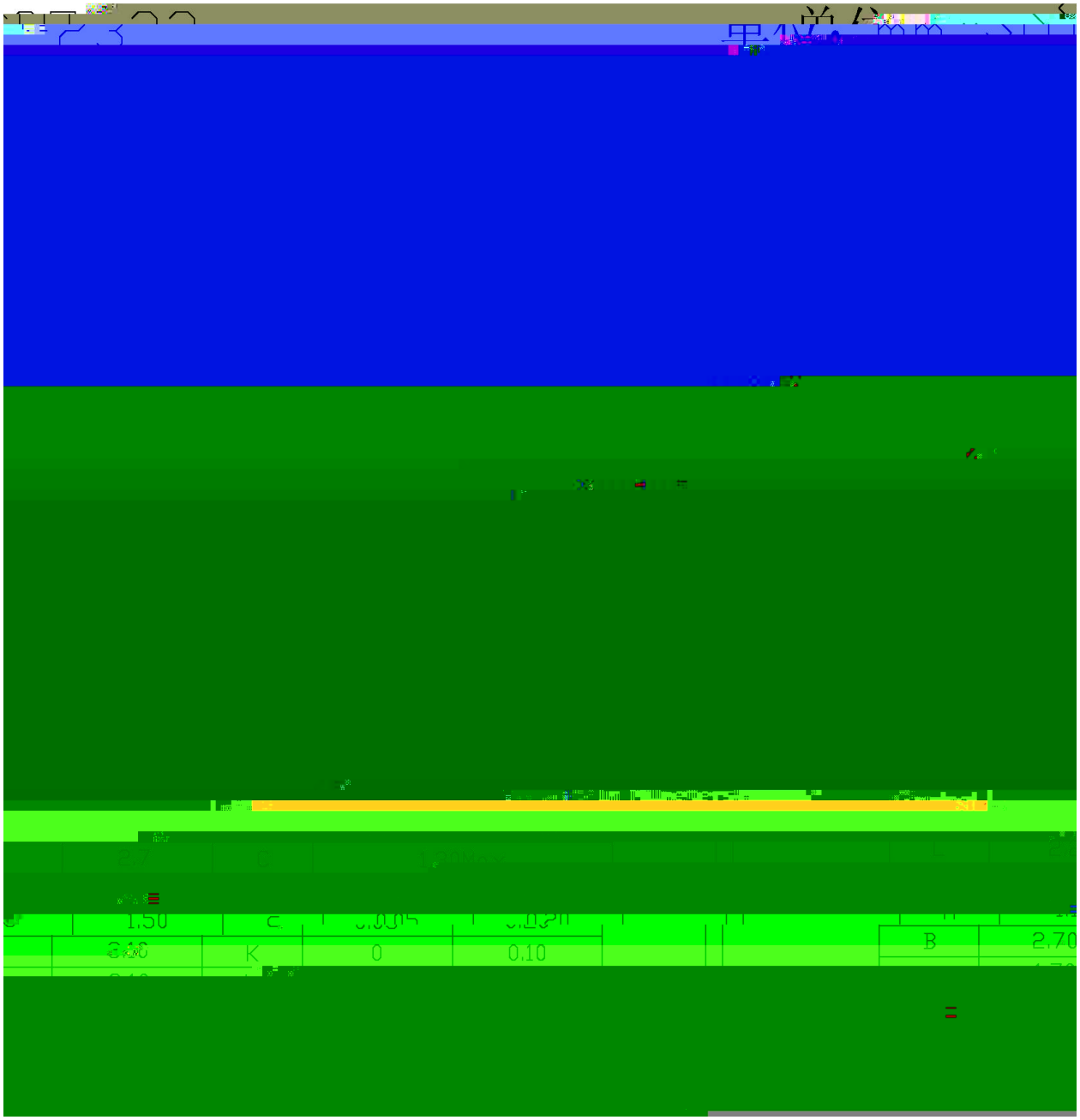
/ Electrical Characteristic Curve



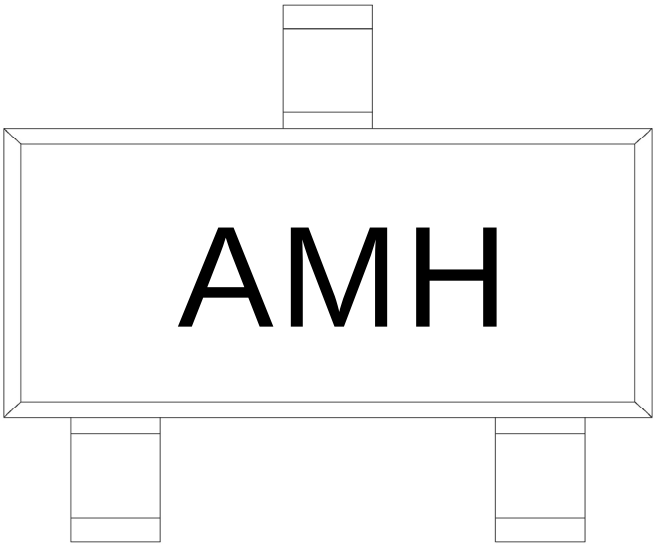




/ Package Dimensions



/ Marking Instructions



H:

AM

Note:

H	Company Code
AM:	Product Type

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

				Note:
1	150	180	60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5		5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3		2 10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units	Dimension	(unit mm³)